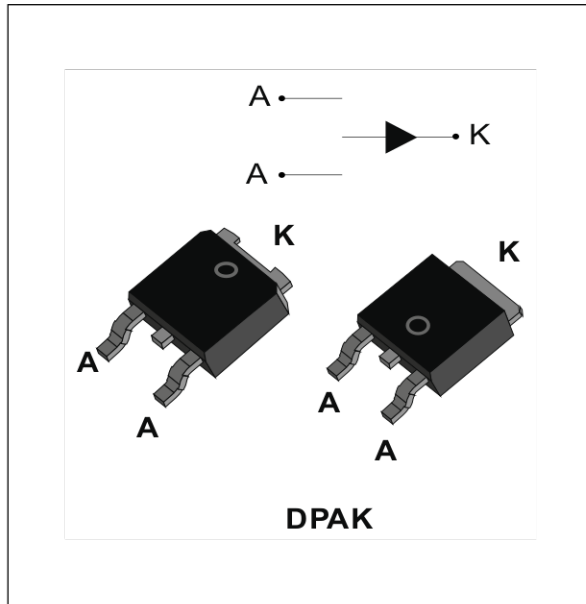


Power Schottky rectifier

Datasheet – production data



Description

High voltage Schottky rectifier suited for switch mode power supply and other power converters.

Packaged in DPAK, this device is intended for use in high frequency circuitries where low switching losses is required.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	10 A
V_{RRM}	45 V
T_j	175 °C
$V_{F(typ)}$	0.50 V

Features

- Very small conduction losses
- Extremely fast switching
- Low thermal resistance
- Negligible switching losses
- Low forward voltage drop
- Low capacitance
- Avalanche specification
- ECOPACK^{®2} compliant component for DPAK on demand

1 Characteristics

Table 2. Absolute ratings (limiting values, at 25 °C unless otherwise stated)

Symbol	Parameter	Value	Unit	
V _R RM	Repetitive peak reverse voltage	45	V	
I _F (RMS) / pin	Forward rms current	7	A	
I _F (AV)	Average forward current, square wave	T _c = 150 °C, δ = 0.5	10	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	75	A
P _{ARM}	Repetitive peak avalanche power	t _p = 10 μs, T _j = 125 °C	285	W
T _{stg}	Storage temperature range	-65 to + 150	°C	
T _j	Maximum operating junction temperature ⁽¹⁾	175	°C	

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	3	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}		100	μA
		T _j = 125 °C		7	15	mA
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 10 A		0.63	V
		T _j = 125 °C		0.50	0.57	
		T _j = 25 °C	I _F = 20 A		0.84	
		T _j = 125 °C		0.65	0.72	

1. Pulse test: t_p = 5 ms, δ < 2%
 2. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.015 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

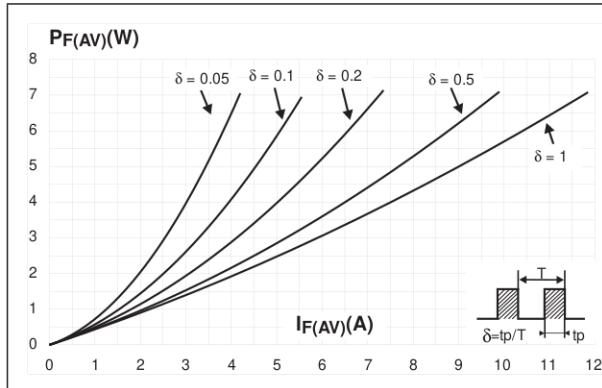


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

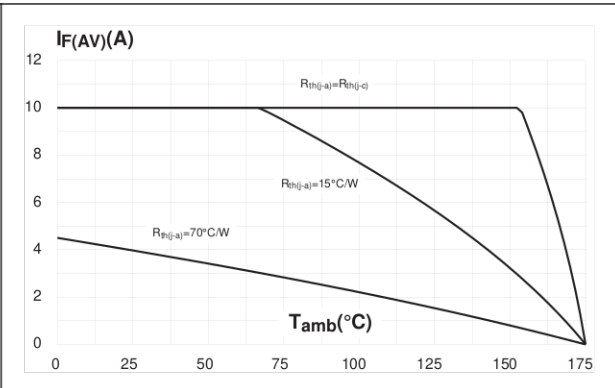


Figure 3. Normalized avalanche power derating versus pulse duration at $T_j = 125^\circ\text{C}$

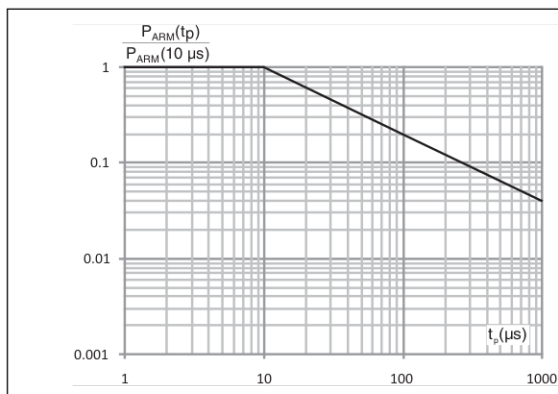


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

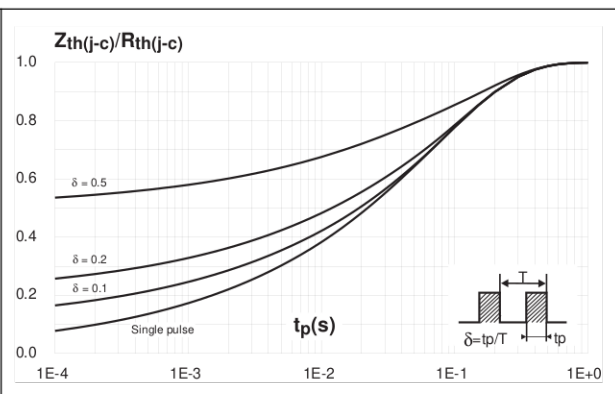


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

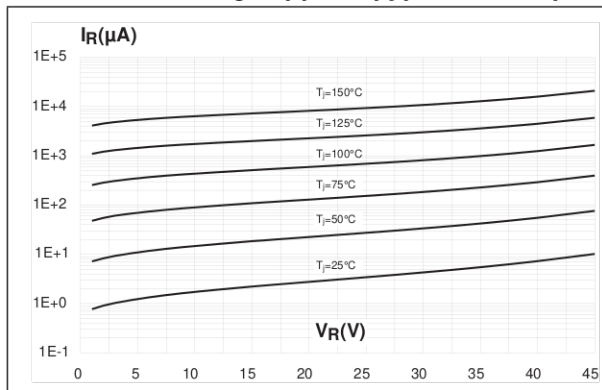


Figure 6. Junction capacitance versus reverse voltage applied (typical values)

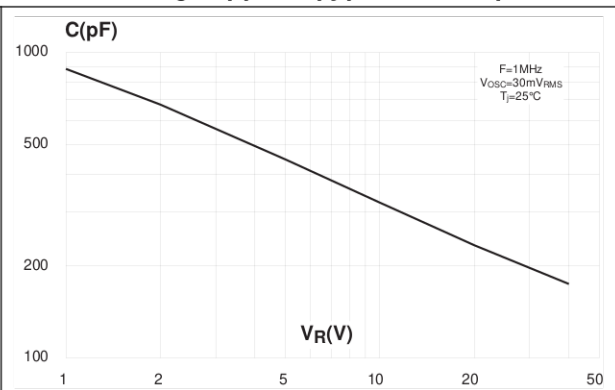


Figure 7. Forward voltage drop versus forward current

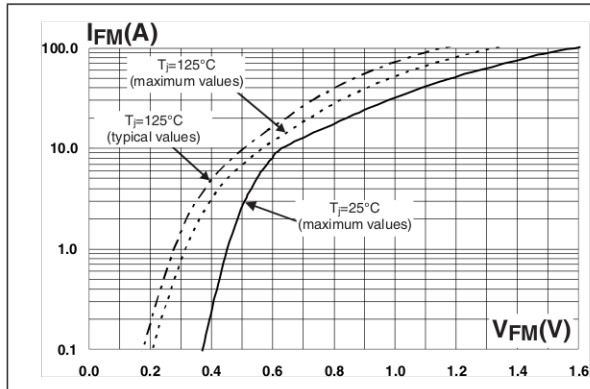
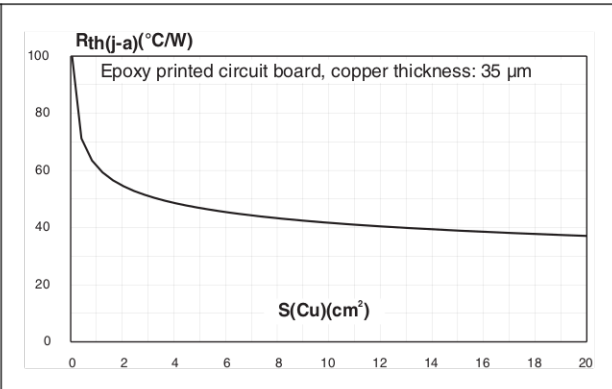


Figure 8. Thermal resistance junction to ambient versus copper surface under tab

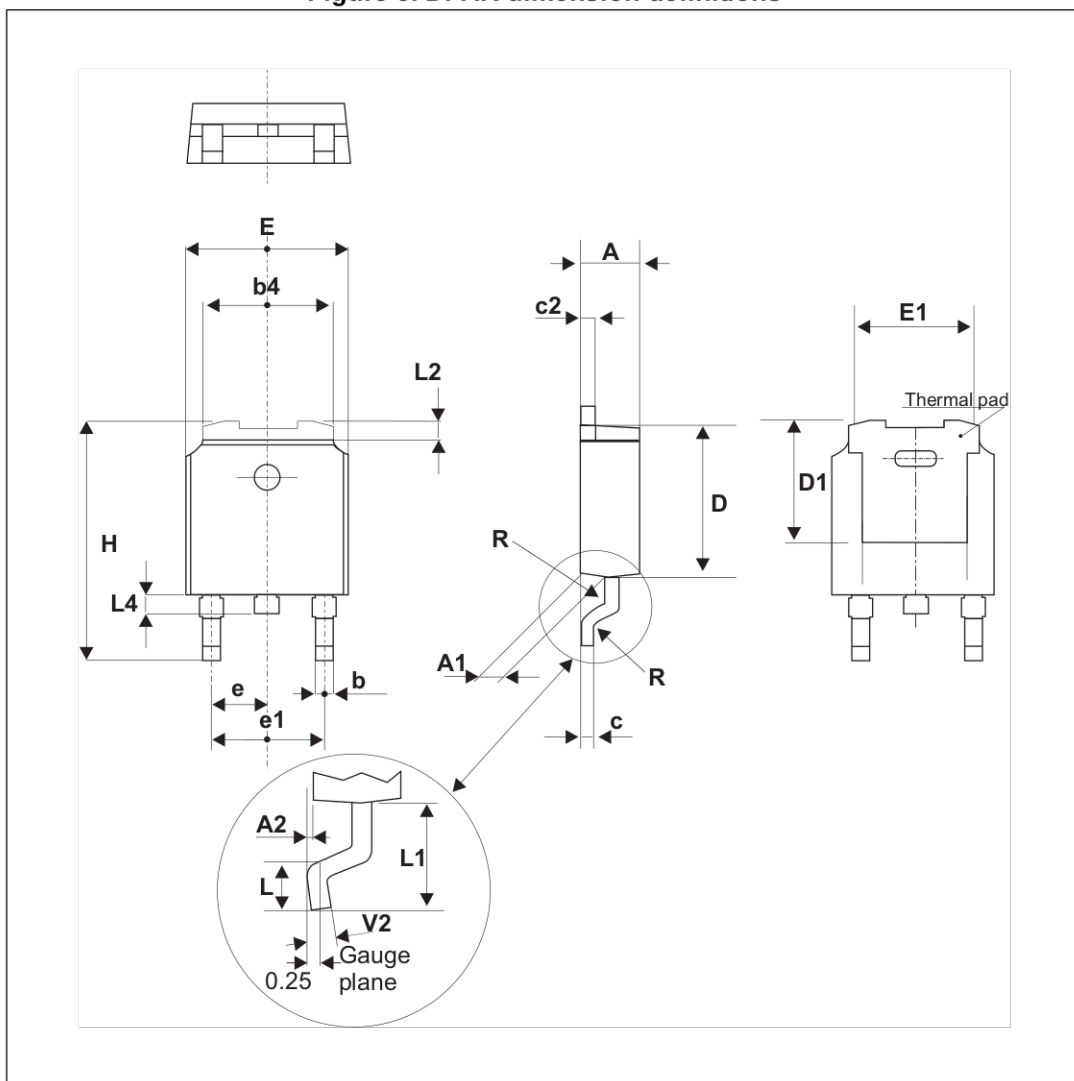


2 Package Information

- Epoxy meets UL94,V0
- Cooling method: by conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 9. DPAK dimension definitions

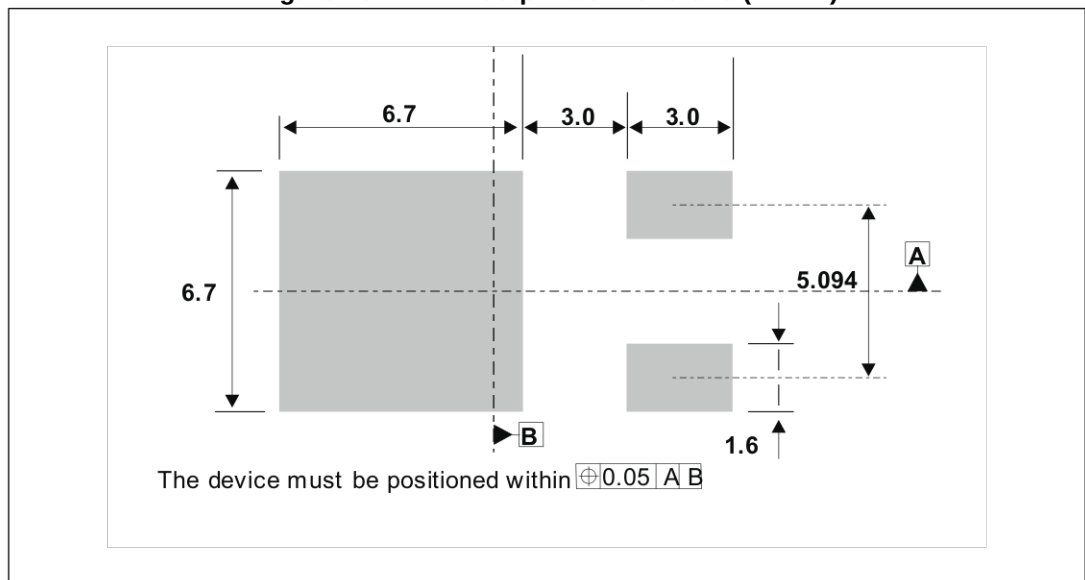


Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5. DPAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.18		2.40	0.085		0.094
A1	0.90		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.01
b	0.64		0.90	0.025		0.035
b4	4.95		5.46	0.195		0.215
c	0.46		0.61	0.018		0.024
c2	0.46		0.60	0.018		0.024
D	5.97		6.22	0.235		0.245
D1	5.10			0.201		
E	6.35		6.73	0.250		0.265
E1	4.32			0.170		
e1	4.4		4.7	0.173		0.185
H	9.35		10.40	0.368		0.407
L	1.0		1.78	0.039		0.070
L2			1.27			0.05
L4	0.6		1.02	0.024		0.040
V2	0°		8°	0°		8°

Figure 10. DPAK footprint dimensions (in mm)



3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1045B	S1045	DPAK	0.30 g	75	Tube
STPS1045B-TR	S1045			2500	Tape and reel

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
Jul-2003	3B	Last issue
21-Apr-2005	4	IPAK package removed
03-Nov-2005	5	DPAK foot print dimensions updated.
01-Jul-2010	6	Updated Figure 8 Updated ECOPACK statement.
04-Nov-2014	7	Updated DPAK package information, Table 2 and Figure 3 . Removed P_{ARM} ($T_j = 25\text{ °C}$).

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